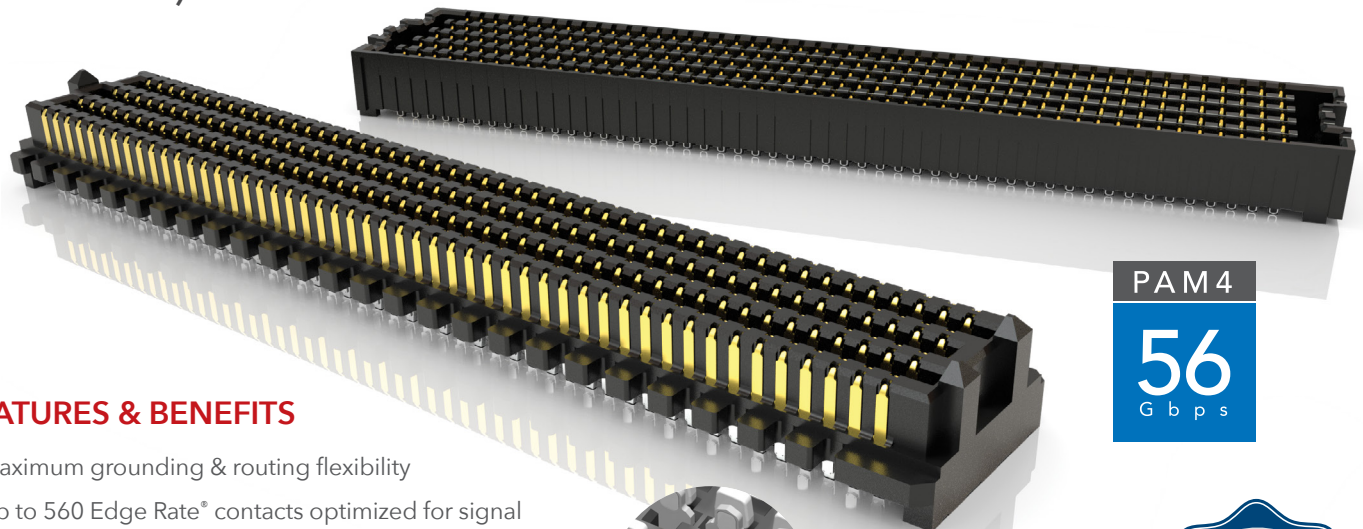




HIGH-DENSITY OPEN-PIN-FIELD ARRAYS

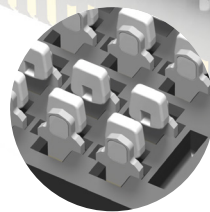
(1.27 mm) .050" PITCH



PAM 4
56
G b p s

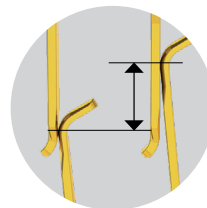
FEATURES & BENEFITS

- Maximum grounding & routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance.
- 7 mm to 40 mm stack heights
- Variety of designs and options: Right-Angle, Guide Posts, 85 Ω Elevated Risers, 85 Ω Tuned, Press-Fit and Press-Fit Right-Angle, Guide Post Field Termination Kits
- Cable mates (SEAC Series) and Jack Screw Standoffs (JSO Series) also available
- Standards: VITA 47, VITA 57.1 FMC, VITA 57.4 FMC+, VITA 74 VNX, PISMO™ 2
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel & InfiniBand™
- Severe Environment Testing qualified (SEAM/SEAF); aligns with MIL-DTL-55302. Visit samtec.com/set



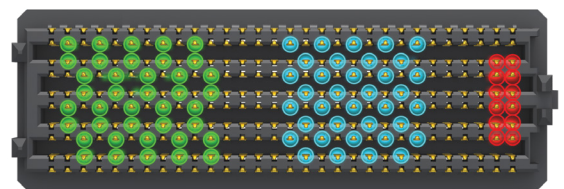
Solder Charges

EDGE RATE
CONTACT



(1.12 mm) .044" Nominal Wipe

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



Differential Pair Single-Ended Power

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
SEAM/SEAF	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC/339 VAC	Yes
SEAM-RA/SEAF-RA	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.9 A (10 pins powered)	240 VAC/339 VAC	Yes
SEAM-GP	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC/339 VAC	Yes
SEAMP/SEAFP	Natural High Temp Nylon	Copper Alloy (SEAMP) BeCu Alloy (SEAFP)	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.9 A (6 pins powered)	255 VAC/361 VAC	Not Available
SEAR	Black LCP	Hard Gold Plated	Au over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.4 A (20 pins powered)	240 VAC/339 VAC	Not Available
SEAMI	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	Not Available	Not Available	Yes

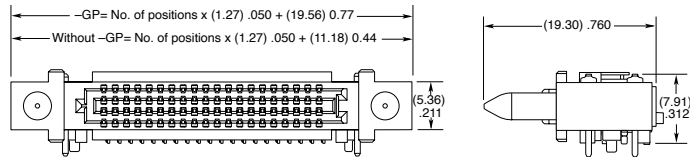
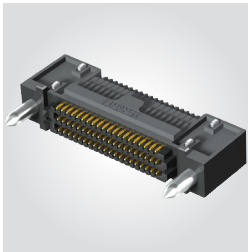
Note: Some lengths, styles and options are non-standard, non-returnable

(1.27 mm) .050" PITCH • RIGHT-ANGLE & GUIDE POST

SERIES	POSITIONS PER ROW	01	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTIONS	"X"R
SEAM Right-Angle Terminal	-20		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04	-1 = Tin/Lead Alloy Solder Charge		-GP = Guide Post/Hole	-TR = Tape & Reel
	-30			-06				
SEAF Right-Angle Socket	-40		-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-08	-2 = Lead-Free Solder Charge		-K = Polyimide Film Pick & Place Pad	-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
	-50			-10				

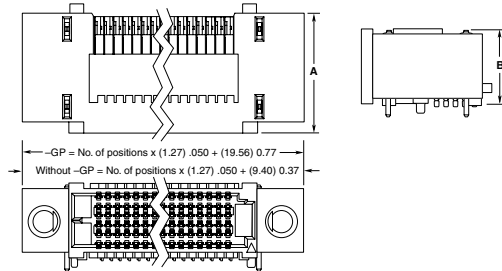
SEAM-RA

Board Mates:
SEAF, SEAF-RA,
SEAFP



SEAF-RA

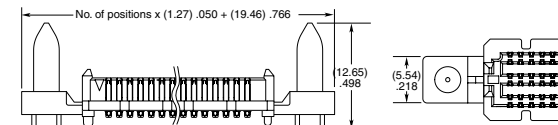
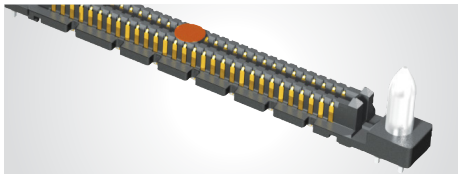
Board Mates:
SEAM, SEAMP



NO. PINS PER ROW	A	B
-04	(13.77) .542	(7.91) .311
-06	(16.31) .642	(10.45) .411
-08	(18.85) .742	(12.99) .511
-10	(21.39) .842	(15.53) .611

View complete specifications at: samtec.com?SEAM-RA & samtec.com?SEAF-RA

SERIES	POSITIONS PER ROW	02.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	GP	K	"X"R
SEAM Terminal with Guide post	-20, -30, -40, -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04	-1 = Tin/Lead Alloy Solder Charge				-TR = Tape & Reel
				-06					
SEAM-GP Board Mates: SEAF-RA-GP			-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-08	-2 = Lead-Free Solder Charge				-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
				-10					



View complete specifications at: samtec.com?SEAM

Note: Some lengths, styles and options are non-standard, non-returnable